

ABSTRACT

A chip-on-film (COF) package and method for image sensor has been disclosed. According to the method a COF film with opening is provided. The COF film has an upper surface, a lower surface and at least an opening. An image sensing chip is flip-chip mounted on the upper surface of the COF film. A transparent glass is bonded to the lower surface of the COF film. The opening is clipped by the transparent glass and the image sensing chip to form a hermetic space. The active surface of the image sensing chip includes an image sensing region toward the transparent glass through the opening and is sealed in the hermetic space by a limited filling material in order to prevent the image sensing region of the image sensing chip from contamination by means of COF tape packaging method.